

CSD96415RWJ 同步降压 NexFET™ 智能功率级

1 特性

- 峰值电流额定值：80 A
- 16V V_{IN} 、25V 额定高侧和低侧 FET
- 峰值效率 ($f_{SW} = 600\text{kHz}$, $L_{OUT} = 150\text{nH}$)：超过 94%
- 工作频率高 (高达 1.75 MHz)
- 温度补偿双向电流感应
- 模拟温度输出
- 故障监控
- 兼容 3.3V 和 5V PWM 信号
- 三态 PWM 输入
- 集成自举开关
- 用于击穿保护的经优化死区时间
- 封装
 - 高密度 5mm x 6mm QFN 封装
 - 超低电感
 - 系统已优化的 PCB 空间占用
 - 耐热增强型顶部散热
 - 符合 RoHS 标准、无铅端子镀层
 - 无卤素
 - 7 英寸和 13 英寸卷带

2 应用

- 多相同步降压转换器
 - 高频应用
 - 大电流、低占空比应用
- 负载点 (POL) 直流/直流转换器
- 存储器和显卡
- 台式机和服务器电压内核同步降压转换器

3 说明

CSD96415RWJ NexFET™ 功率级是一款针对高功率、高密度同步降压转换器进行高度优化的设计。这款产品集成了驱动器器件和功率 MOSFET 来完善功率级开关功能。该组合在小型 5mm x 6mm 外形尺寸封装中提供高电流、高效率和高速开关功能。它还集成了准确电流检测和温度感测功能，以简化系统设计并提高准确度。此外，已对 PCB 封装进行了优化以帮助减少设计时间并简化总体系统设计的完成。

器件信息

器件型号 ⁽¹⁾	封装	封装尺寸
CSD96415RWJ	QFN	5.00mm x 6.00mm
CSD96415RWJT		

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

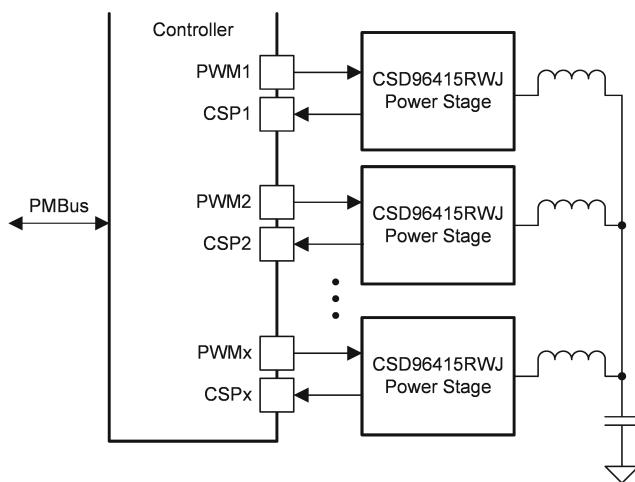


图 3-1. 简化版应用



本文档旨在为方便起见，提供有关 TI 产品中文版本的信息，以确认产品的概要。有关适用的官方英文版本的最新信息，请访问 www.ti.com，其内容始终优先。TI 不保证翻译的准确性和有效性。在实际设计之前，请务必参考最新版本的英文版本。

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4 Revision History

注：以前版本的页码可能与当前版本的页码不同

DATE	REVISION	NOTES
January 2023	*	Initial release

5 Device and Documentation Support

5.1 Documentation Support

5.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

5.3 支持资源

[TI E2E™ 支持论坛](#)是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [《使用条款》](#)。

5.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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5.5 Electrostatic Discharge Caution

 This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

5.6 术语表

[TI 术语表](#)

本术语表列出并解释了术语、首字母缩略词和定义。

6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-frame navigation.

6.1 Packaging Information

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish ⁽⁴⁾	MSL Peak Temp ⁽³⁾	Op Temp (°C)	Device Marking ^{(5) (6)}
CSD96415RWJ	ACTIVE	VQFN-CLIP	RWJ	41	2500	Green (RoHS-Exempt & no Sb/Br)	NIPDAU	Level-2-260C-1 YEAR	-55 to 150	96415RWJ
CSD96415RWJT	ACTIVE	VQFN-CLIP	RWJ	41	250	Green (RoHS-Exempt & no Sb/Br)	NIPDAU	Level-2-260C-1 YEAR	-55 to 150	96415RWJ

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PRE_PROD Unannounced device, not in production, not available for mass market, nor on the web, samples not available.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

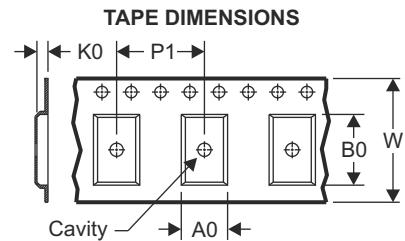
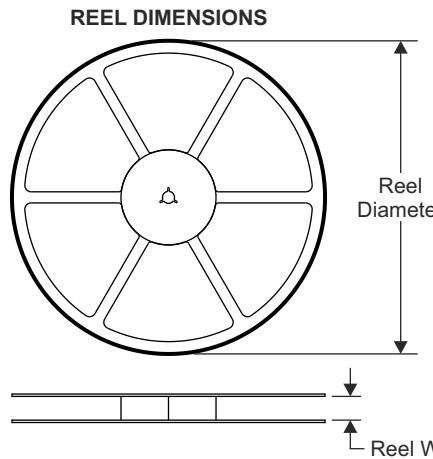
(5) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device

(6) Multiple Device markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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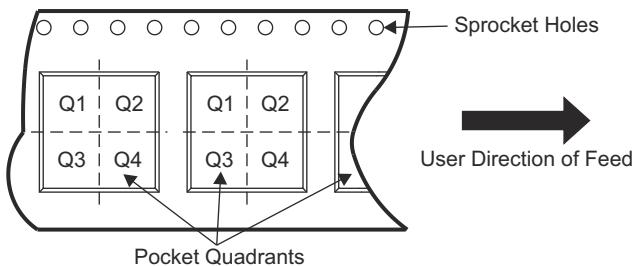
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6.2 Tape and Reel Information



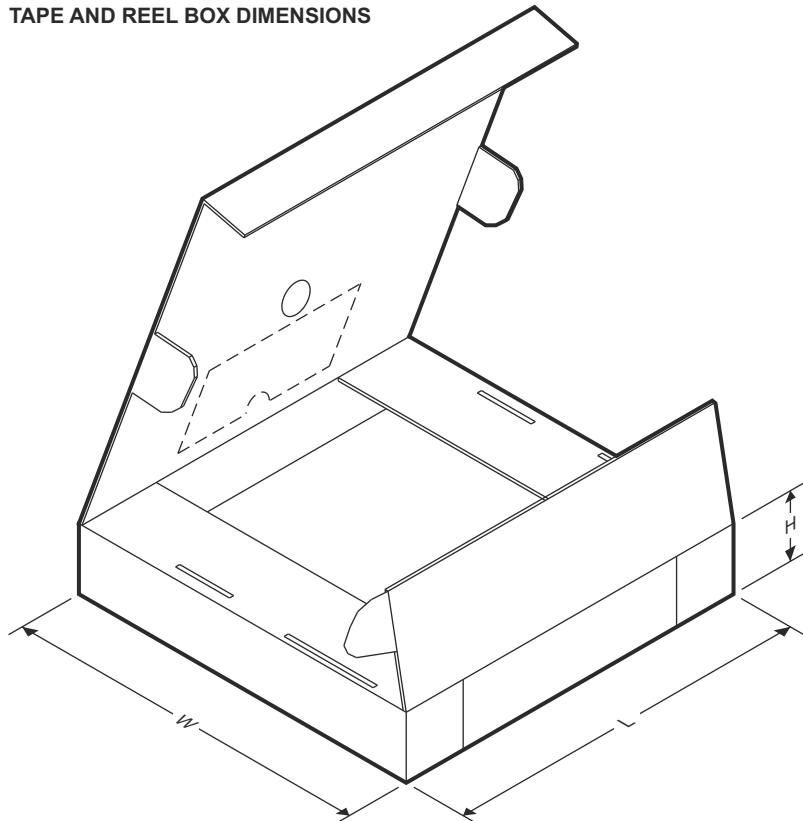
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



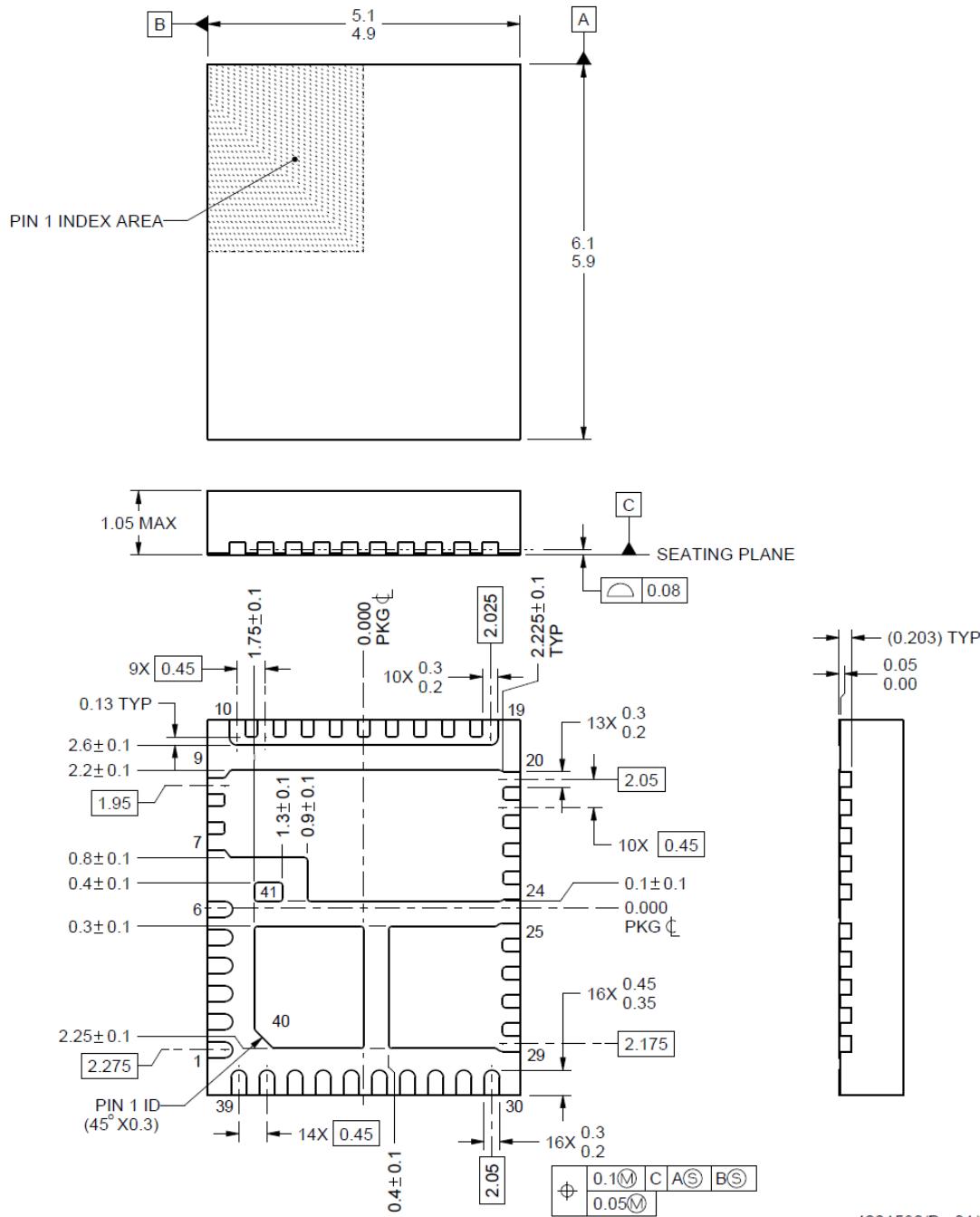
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CSD96415RWJ	VQFN-CLIP	RWJ	41	2500	330	12.4	5.30	6.30	1.20	8.00	12.00	Q1
CSD96415RWJT	VQFN-CLIP	RWJ	41	250	180	12.4	5.30	6.30	1.20	8.00	12.00	Q1

TAPE AND REEL BOX DIMENSIONS



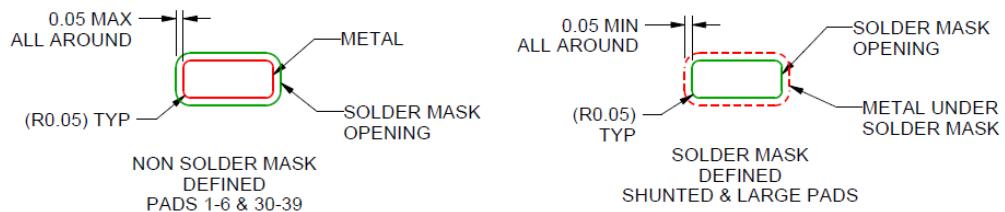
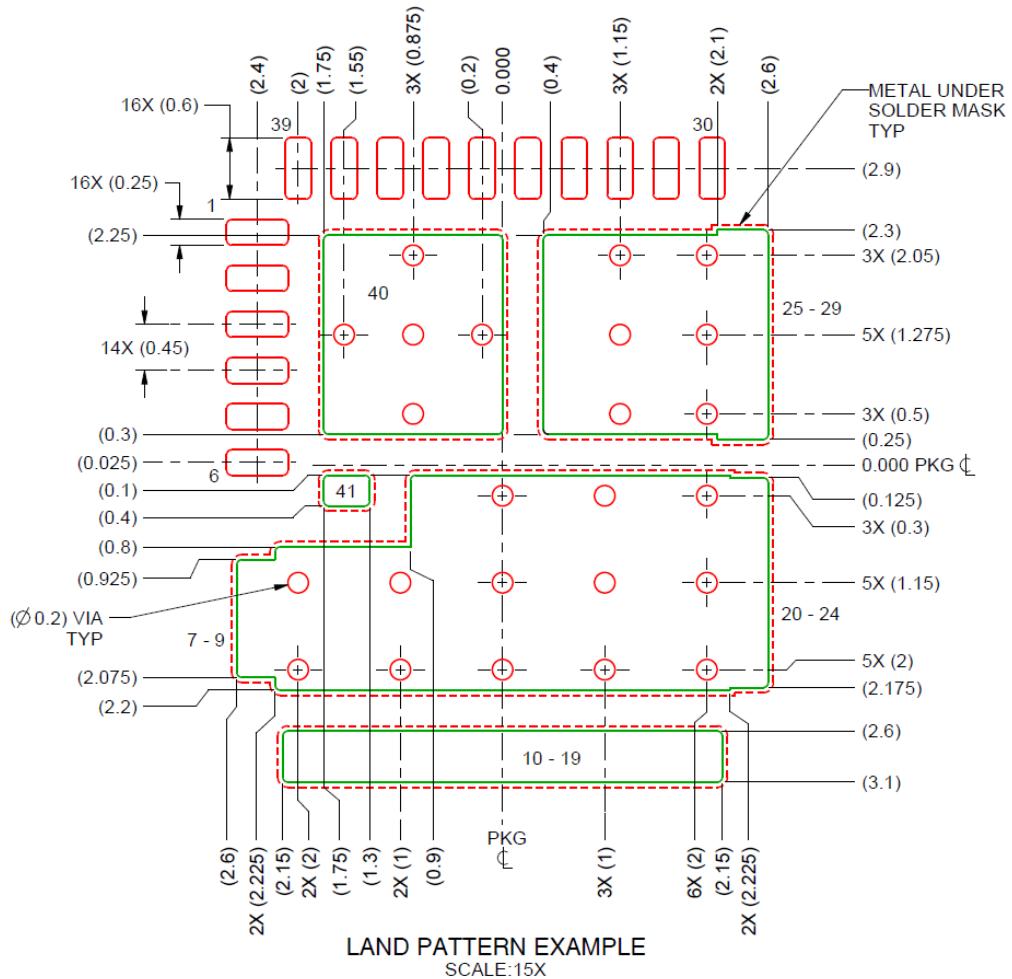
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CSD96415RWJ	VQFN-CLIP	RWJ	41	2500	367	367	38
CSD96415RWJT	VQFN-CLIP	RWJ	41	250	213	191	35

6.3 Mechanical Drawing



- A. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- B. This drawing is subject to change without notice.
- C. The package thermal pads must be soldered to the printed circuit board for optimal thermal and mechanical performance.

6.4 Recommended PCB Land Pattern

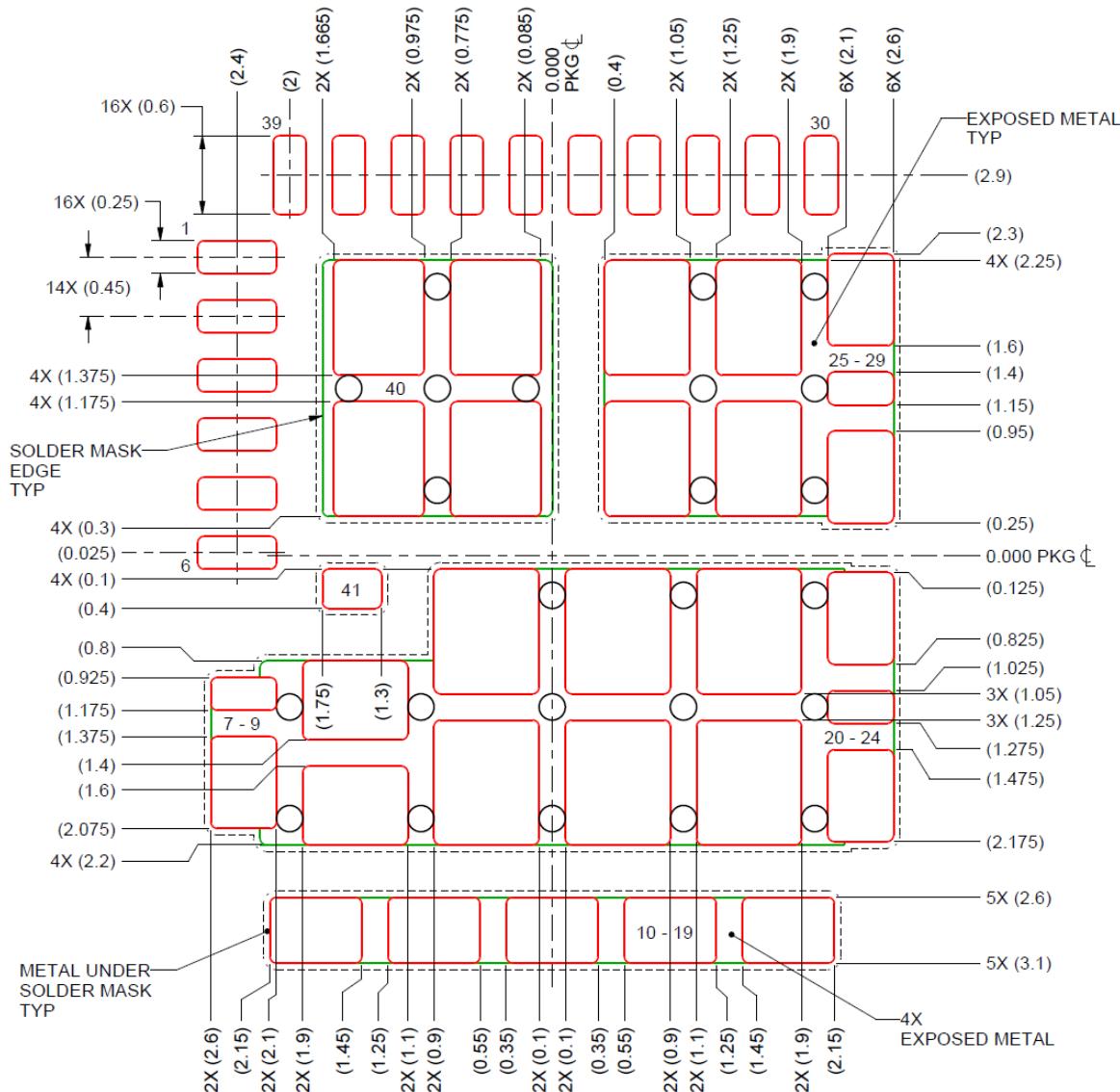


SOLDER MASK DETAILS

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- A. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- B. This drawing is subject to change without notice.
- C. This package is designed to be soldered to thermal pads on the board. For more information, see QFN/SON PCB Attachment (SLUA271).

6.5 Recommended Stencil Opening



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD
71% PRINTED SOLDER COVERAGE BY AREA
SCALE:20X

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- A. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- B. This drawing is subject to change without notice.
- C. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CSD96415RWJ	Active	Production	VQFN-CLIP (RWJ) 41	2500 LARGE T&R	ROHS Exempt	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	96415RWJ
CSD96415RWJT	Active	Production	VQFN-CLIP (RWJ) 41	250 SMALL T&R	ROHS Exempt	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	96415RWJ

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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